Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	3666	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 20:50
L4	1738	257/783	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 21:13
L5	1139	257/679	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 21:55
L6	1148	257/684	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 22:15
L7	2510	257/690	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 22:21
L8	2491	257/698	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 22:31
L9	1527	235/441	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 22:47
L10	2598	343/895	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 22:54

L11	3489	343/700MS	US-PGPUB;	OR	OFF	2005/11/23 22:55
	3103	313)700113	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OK	OH	2003/11/23 22.33
S1	29775	(semiconductor or die or dice or chip or IC) and antenna	USPAT	OR	ON	2005/11/17 16:44
S2	93206	(semiconductor or die or dice or chip or IC) and (antenna or induct\$4)	USPAT	OR	ON	2005/11/17 16:45
S3	8828	(semiconductor or die or dice or chip or IC) same (antenna)	USPAT	OR	ON	2005/11/23 15:22
S4	362	(semiconductor or die or dice or chip or IC) with (transceiv\$3) same (antenna)	USPAT	OR	ON	2005/11/21 11:55
S5	2434	(semiconductor or die or dice or chip or IC) and pad with (dual or double)	USPAT	OR	ON	2005/11/21 11:56
S6	185	(semiconductor or die or dice or chip or IC) and pad with (dual or double) same solder	USPAT	OR	ON	2005/11/21 12:01
S7	798	(semiconductor or die or dice or chip or IC) and pad with (separat\$3 or devid\$3) same solder	USPAT	OR	ON	2005/11/21 12:25
S8	1	"5162264".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:09
S9	1	"5220199".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:10
S10	1	"5726501".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:10
S11	40	(semiconductor or die or dice or chip or IC) and pad with (separat\$3 or devid\$3) same solder	JPO	OR	ON	2005/11/21 12:27
S12	290	(semiconductor or die or dice or chip or IC) and pad with (pattern\$3) same solder	JPO	OR	ON	2005/11/21 12:36
S13	0	chris with chu	JPO	OR	ON	2005/11/21 12:36
S14	2	"6,239,752".pn. or "6,424,315". pn.	USPAT	OR	OFF	2005/11/23 13:28
S15	1990	(semiconductor or die or dice or chip or IC) with (bumps or connect\$3 or balls or pillars or columns) same (antenna)	USPAT	OR	ON	2005/11/23 17:24

S16	6	("5528222" "5856662" "6281048" "6374486" "6435415" "6677186").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/23 15:26
S17	79	(semiconductor or die or dice or chip or IC) with (fill\$3 or underfill) same (antenna)	USPAT	OR	ON	2005/11/23 15:32
S18	8	("4736454" "4987425" "5185613" "5386214" "5400039" "5438697" "5448249" "5510758").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/23 15:45
S19	12	("5386214").URPN.	USPAT	OR	OFF	2005/11/23 15:48
S20	107	S15 and (antenna or coil) with (both or dual) with surfaces	USPAT	OR	ON	2005/11/23 17:56
S21	1	"20050167797"	US-PGPUB; USPAT	OR	ON	2005/11/23 17:56